

09/836,182

3/20/02

FILE 'HCAPLUS' ENTERED AT 09:51:18 ON 20 MAR 2002

L1 70 S TAPE AND WATER(2A)PERMEABILITY
L2 213 S TAPE(2A)(PORE OR POROSIT### OR POROUS####)
L3 1 S L2 AND (WATER OR H2O OR AQ)(2A)PERMEABILITY
L4 78 S TAPE AND (WATER OR H2O OR AQ)(2A)PERMEABILITY
L5 77 S L4 NOT L3
L6 18 S TAPE(4A)(WATER OR H2O OR AQ) AND TAPE(4A)PERMEABILITY

FILE 'REGISTRY' ENTERED AT 10:04:41 ON 20 MAR 2002

L7 39 S WATER/CN OR H2 O/MF

FILE 'HCAPLUS' ENTERED AT 10:05:30 ON 20 MAR 2002

L8 2331 S L7(L)PERMEABILITY
L9 6910 S (VAPOR OR VAPOUR OR MOISTURE)(5A)PERMEABILITY
L10 4041 S (MOIST##### OR HUMID##### OR STEAM)(5A)PE
RMEABILITY
L11 6225 S L9 AND (MOIST##### OR L7 OR AQ OR STEAM OR HUMID##### OR W
L12 676 S AQ(5A)PERMEABILITY
L13 9191 S L8 OR (L10 OR L11 OR L12)
L14 2693 S L13 AND (24 OR 24H OR DAY OR HOUR OR M224H
OR M224 OR CM224##### OR FT224##### OR IN224#####)
L15 62 S L14 AND TAPE
L16 58 S L15 NOT L6
L17 5 S L16 AND (CHIP OR WAFER OR SEMICOND#####
OR IC OR ICS OR CIRCUIT### OR PCB OR BOARD OR ELECTRONIC###)
L18 53 S L16 NOT L17
L19 41 S L18 AND G M2
L20 3 S L13 AND (TAB OR (TAPE(2A)BOND### OR
SOLDER BALL))
L21 374 S TAPE AUTOMATED BONDING
L22 1 S L21 AND PERMEABILITY
L23 46 S PRINTED CIRCUIT BOARDS AND PERMEABILITY
L24 20 S L23 AND (MOIST##### OR L7 OR AQ OR STEAM
OR HUMID##### OR WATER OR H2O)
L25 3 S L23 AND (SOLDER##### OR BALL)
L26 3645 S MOUNT###(2A)(SEMICONDUCT##### OR CHIP OR
WAFER OR PACKAG###)
L27 1 S L26 AND L13

FILE 'INSPEC' ENTERED AT 10:46:17 ON 20 MAR 2002

E TAPE AUTOMATED/CT

E E4+ALL/CT

L28 114975 S (MICROASSEMBLING/CT OR "MANUFACTURING
PROCESSES"/CT OR "JOINING PROCESSES"/CT OR WELDING/CT OR "LEAD
BONDING"/CT OR PACKAGING/CT OR "TAPE AUTOMATED BONDING"/CT OR
TAB/CT OR "THERMOCOMPRESSION BONDING"/CT OR "THERMOSONIC
BONDING"/CT OR "FINE-PITCH TECHNOLOGY"/CT OR "HYBRID INTEGRATED
CIRCUITS"/CT OR "INTEGRATED CIRCUIT TECHNOLOGY"/CT OR
"PLASTIC PACKAGING"/CT OR "PRINTED CIRCUIT MANUFACTURE"/CT OR
"SURFACE MOUNT TECHNOLOGY"/CT OR VLSI/CT OR "LEAD BONDING"/CT
OR PACKAGING/CT) OR (B0170J OR B2240)/CT OR BGA OR BALLGRID OR
BALL GRID OR TAB OR AUTOMATED BONDING
L29 1705 S MOUNT###(2A)(SEMICONDUCT##### OR CHIP OR WAFER)
L30 114 S (L28 OR L29) AND PERMEABILITY
L31 1 S L30 AND TAPE
L32 42 S L30 AND (ADHER### OR ADHES##### OR TAB
OR FILM OR STRIP)

09/836,182

3/20/02

FILE 'INSPEC, PIRA, RAPRA, JICST-EPLUS, COMPENDEX, CEABA-VTB, WPIX, JAPIO, SCISEARCH, INSPHYS' ENTERED AT 11:04:37 ON 20 MAR 2002

L35 319 S (MOIST##### OR HUMID##### OR STEAM OR AQ
OR WATER OR H2O)(3A) PERMEABILITY AND TAPE
L36 3 S L35 AND (BALLGRID OR BALL GRID OR TAB OR
TAPE AUTOMAT### OR AUTOMAT### BONDING OR BGA)
L37 194740 S (BALLGRID OR BALL GRID OR TAB OR TAPE
AUTOMAT### OR AUTOMAT### BONDING OR BGA)
L38 27837 S (MOIST##### OR HUMID##### OR STEAM OR AQ
OR WATER OR H2O)(3A) PERMEABILITY
L39 177 S L37 AND L38
L40 177 DUP REM L39 (0 DUPLICATES REMOVED)
L41 1003 S TAPE(3A)(PERMEAB##### OR PORE OR POROUS
OR POROS#####)
L42 0 S L40 AND L41
L43 82330 S (ADHER##### OR ADHES##### OR FILM OR
LAYER OR STRIP)(3A)(PERMEAB##### OR PORE OR POROUS OR
POROS#####)
L44 33 S L40 AND L43
L45 697 S L38 AND (SEMICONDUCT##### OR CHIP OR IC
OR ICS OR CIRCUIT## OR PCB OR PCBs OR WAFER)
L46 167 S L45 AND (TAPE OR ADHER##### OR ADHES#####
OR MOUNT##### OR BGA OR BALL OR BALLGRID)
L47 32 S L46 AND (24 OR 24H OR 24HR OR DAY OR HR)
L48 30 DUP REM L47 (2 DUPLICATES REMOVED)